

**Change Of Attorney Or Agent's Address In Application  
(37 CFR 1.8(a))**

Docket No. #17  
S. Sand  
0112857-118

In Re Application Of: Hachiya, et al.



Serial No.  
08/992,770

Filing Date  
December 17, 1997

Examiner  
T. Vu

Group Art Unit  
2756

Invention: **METHOD AND APPARATUS FOR AUTOMATIC SENDING OF E-MAIL AND AUTOMATIC SENDING CONTROL PROGRAM SUPPLYING MEDIUM**

**TO THE ASSISTANT COMMISSIONER FOR PATENTS**

Please send all correspondence for this application to:

William E. Vaughan  
Bell, Boyd & Lloyd LLC  
P.O. Box 1135  
Chicago, Illinois 60690-1135

Please direct all telephone calls to:

William E. Vaughan (312) 807-4292

The firm of Limbach & Limbach is in the process of dissolution. Bell, Boyd & Lloyd has taken over prosecution of this case.

*[Signature]*  
*Signature of Attorney or Agent of Record*

Timothy L. Harney (Reg. No. 38,174)  
Bell, Boyd & Lloyd LLC  
P.O. Box 1135  
Chicago, Illinois 60690-1135

*Registration Number & Address of Attorney or Agent of Record*

Dated: *3/12/01*

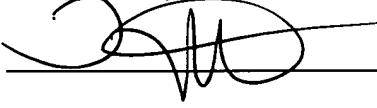
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20231.

*[Signature]*  
*Signature of Person Mailing Correspondence*

*Timothy L. Harney*  
*Typed or Printed Name of Person Mailing Correspondence*

If any additional fees are due in connection with this application as a whole, the office is authorized to deduct said fees from Deposit Account 02-1818. If such a withdrawal is made, please indicate the Attorney Docket No. (0112857-118) on the account statement.

Respectfully submitted,



(Reg. No. 38,174)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on 3/12/01.

